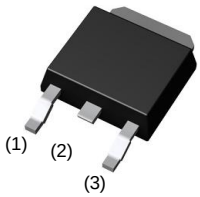
# RDD022N60

**Nch 600V 2A Power MOSFET** Datasheet

| | |
|---|---|
| $V_{DSS}$ | 600V |
| $R_{DS(on)}$ (Max.) | 6.7Ω |
| $I_D$ | 2A |
| $P_D$ | 20W |

## ●Outline

CPT3
(SC-63)
(SOT-428)




## ●Features

1) Low on-resistance.

2) Fast switching speed.

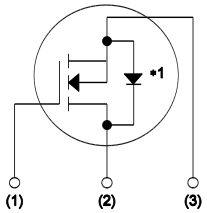
3) Gate-source voltage ($V_{GSS}$) guaranteed to be ±30V.

4) Drive circuits can be simple.

5) Parallel use is easy.

6) Pb-free lead plating ; RoHS compliant

## ●Inner circuit




(1) Gate
(2) Drain
(3) Source

*1 BODY DIODE

## ●Application

Switching Power Supply

## ●Packaging specifications

| | | |
|---|---|---|
| Type | Packaging | Taping |
| | Reel size (mm) | 330 |
| | Tape width (mm) | 16 |
| | Basic ordering unit (pcs) | 2,500 |
| | Taping code | TL |
| | Marking | 022N60 |

## ●Absolute maximum ratings($T_a$ = 25°C)

| Parameter | | Symbol | Value | Unit |
|---|---|---|---|---|
| Drain - Source voltage | | $V_{DSS}$ | 600 | V |
| Continuous drain current | $T_c$ = 25°C | $I_D$ *1 | ±2.0 | A |
| | $T_c$ = 100°C | $I_D$ *1 | 1.0 | A |
| Pulsed drain current | | $I_{D,pulse}$ *2 | ±6.0 | A |
| Gate - Source voltage | | $V_{GSS}$ | ±30 | V |
| Avalanche energy, single pulse | | $E_{AS}$ *3 | 1.4 | mJ |
| Avalanche energy, repetitive | | $E_{AR}$ *4 | 1.1 | mJ |
| Avalanche current | | $I_{AR}$ *3 | 2.0 | A |
| Power dissipation ($T_c$ = 25°C) | | $P_D$ | 20 | W |
| Junction temperature | | $T_j$ | 150 | °C |
| Range of storage temperature | | $T_{stg}$ | −55 to +150 | °C |
| Reverse diode dv/dt | | dv/dt *5 | 15 | V/ns |

## ●Absolute maximum ratings

| Parameter | Symbol | Conditions | Values | Unit |
|---|---|---|---|---|
| Drain - Source voltage slope | dv/dt | $V_{DS}$ = 480V, $I_D$ = 2A<br>$T_j$ = 125°C | 50 | V/ns |

## ●Thermal resistance

| Parameter | Symbol | Values | | | Unit |
|---|---|---|---|---|---|
| | | Min. | Typ. | Max. | |
| Thermal resistance, junction - case | $R_{thJC}$ | - | - | 6.25 | °C/W |
| Thermal resistance, junction - ambient | $R_{thJA}$ | - | - | 100 | °C/W |
| Soldering temperature, wavesoldering for 10s | $T_{sold}$ | - | - | 265 | °C |

## ●Electrical characteristics($T_a$ = 25°C)

| Parameter | Symbol | Conditions | Values | | | Unit |
|---|---|---|---|---|---|---|
| | | | Min. | Typ. | Max. | |
| Drain - Source breakdown voltage | $V_{(BR)DSS}$ | $V_{GS}$ = 0V, $I_D$ = 1mA | 600 | - | - | V |
| Drain - Source avalanche breakdown voltage | $V_{(BR)DS}$ | $V_{GS}$ = 0V, $I_D$ = 2A | - | 700 | - | V |
| Zero gate voltage drain current | $I_{DSS}$ | $V_{DS}$ = 600V, $V_{GS}$ = 0V<br>$T_j$ = 25°C<br>$T_j$ = 125°C | -<br>- | 0.1<br>- | 100<br>1000 | μA |
| Gate - Source leakage current | $I_{GSS}$ | $V_{GS}$ = ±30V, $V_{DS}$ = 0V | - | - | ±100 | nA |
| Gate threshold voltage | $V_{GS\ (th)}$ | $V_{DS}$ = 10V, $I_D$ = 1mA | 2.5 | - | 4.7 | V |
| Static drain - source on - state resistance | $R_{DS(on)}$ *6 | $V_{GS}$ = 10V, $I_D$ = 1A<br>$T_j$ = 25°C<br>$T_j$ = 125°C | -<br>- | 5.2<br>10.4 | 6.7<br>- | Ω |
| Gate input resistance | $R_G$ | f = 1MHz, open drain | - | 9.5 | - | Ω |

## ●Electrical characteristics($T_a$ = 25°C)

| Parameter | Symbol | Conditions | Values | | | Unit |
|---|---|---|---|---|---|---|
| | | | Min. | Typ. | Max. | |
| Transconductance | $g_{fs}$ *6 | $V_{DS}$ = 10V, $I_D$ = 1A | 0.5 | 1.2 | - | S |
| Input capacitance | $C_{iss}$ | $V_{GS}$ = 0V | - | 175 | - | pF |
| Output capacitance | $C_{oss}$ | $V_{DS}$ = 25V | - | 25 | - | |
| Reverse transfer capacitance | $C_{rss}$ | f = 1MHz | - | 3 | - | |
| Effective output capacitance, energy related | $C_{o(er)}$ | $V_{GS}$ = 0V<br>$V_{DS}$ = 0V to 480V | - | 8.34 | - | pF |
| Effective output capacitance, time related | $C_{o(tr)}$ | | - | 12.8 | - | |
| Turn - on delay time | $t_{d(on)}$ *6 | $V_{DD}$ ≃ 300V, $V_{GS}$ = 10V | - | 17 | - | ns |
| Rise time | $t_r$ *6 | $I_D$ = 1A | - | 14 | - | |
| Turn - off delay time | $t_{d(off)}$ *6 | $R_L$ = 300Ω | - | 25 | 50 | |
| Fall time | $t_f$ *6 | $R_G$ = 10Ω | - | 53 | 106 | |

## ●Gate Charge characteristics($T_a$ = 25°C)

| Parameter | Symbol | Conditions | Values | | | Unit |
|---|---|---|---|---|---|---|
| | | | Min. | Typ. | Max. | |
| Total gate charge | $Q_g$ *6 | $V_{DD}$ ≃ 300V | - | 7 | - | nC |
| Gate - Source charge | $Q_{gs}$ *6 | $I_D$ = 2A | - | 2.1 | - | |
| Gate - Drain charge | $Q_{gd}$ *6 | $V_{GS}$ = 10V | - | 3.2 | - | |
| Gate plateau voltage | $V_{(plateau)}$ | $V_{DD}$ ≃ 300V, $I_D$ = 2A | - | 6.2 | - | V |

*1 Limited only by maximum temperature allowed.

*2 $P_W$ ≤ 10μs, Duty cycle ≤ 1%

*3 L ≃ 500μH, $V_{DD}$ = 50V, $R_G$ = 25Ω, starting $T_j$ = 25°C

*4 L ≃ 500μH, $V_{DD}$ = 50V, $R_G$ = 25Ω, starting $T_j$ = 25°C, f = 10kHz

*5 Reference measurement circuits Fig.5-1.

*6 Pulsed

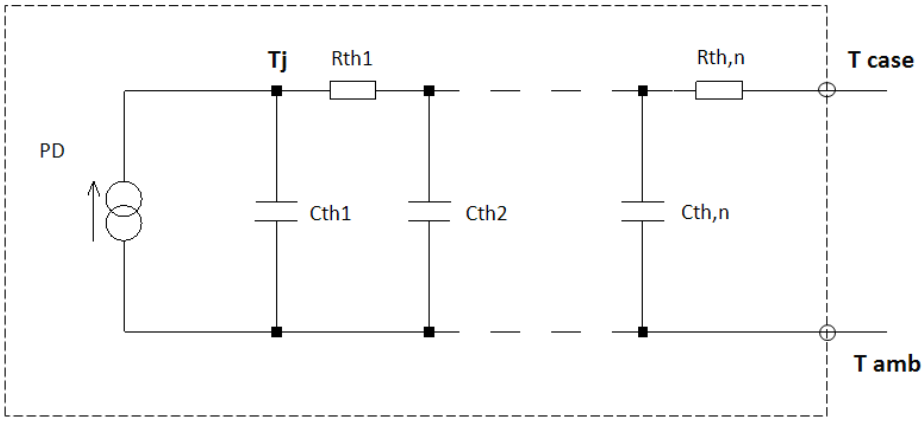
## ●Body diode electrical characteristics (Source-Drain)($T_a$ = 25°C)

| Parameter | Symbol | Conditions | Values | | | Unit |
|---|---|---|---|---|---|---|
| | | | Min. | Typ. | Max. | |
| Inverse diode continuous, forward current | $I_S$ *1 | $T_c$ = 25°C | - | - | 2 | A |
| Inverse diode direct current, pulsed | $I_{SM}$ *2 | | - | - | 6 | A |
| Forward voltage | $V_{SD}$ *6 | $V_{GS}$ = 0V, $I_S$ = 2A | - | - | 1.5 | V |
| Reverse recovery time | $t_{rr}$ *6 | $I_S$ = 2A<br>di/dt = 100A/μs | - | 486 | - | ns |
| Reverse recovery charge | $Q_{rr}$ *6 | | - | 1.35 | - | μC |
| Peak reverse recovery current | $I_{rrm}$ *6 | | - | 5.5 | - | A |
| Peak rate of fall of reverse recovery current | $di_{rr}/dt$ | $T_j$ = 25°C | - | 70 | - | A/μs |

## ●Typical Transient Thermal Characteristics

| Symbol | Value | Unit |
|---|---|---|
| $R_{th1}$ | 1.16 | K/W |
| $R_{th2}$ | 2.24 | |
| $R_{th3}$ | 21.5 | |
| $R_{th4}$ | 48.1 | |

| Symbol | Value | Unit |
|---|---|---|
| $C_{th1}$ | 0.00194 | Ws/K |
| $C_{th2}$ | 0.0115 | |
| $C_{th3}$ | 0.14 | |
| $C_{th4}$ | 1.24 | |



## ●Electrical characteristic curves

Fig.1 Power Dissipation Derating Curve

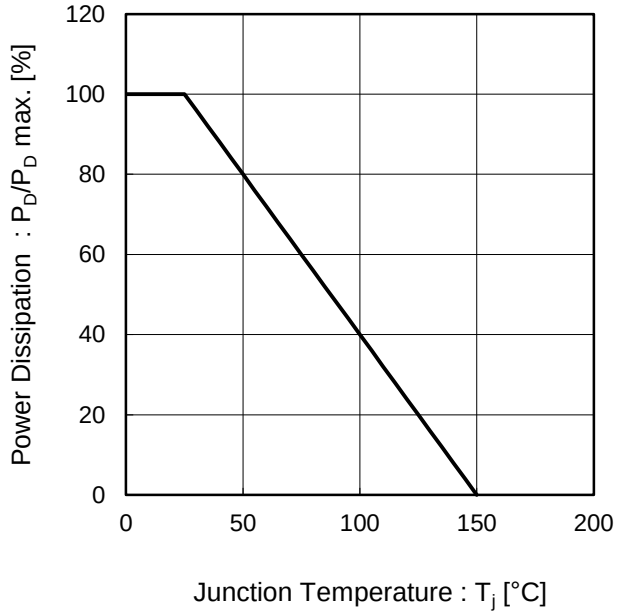



Fig.2 Maximum Safe Operating Area

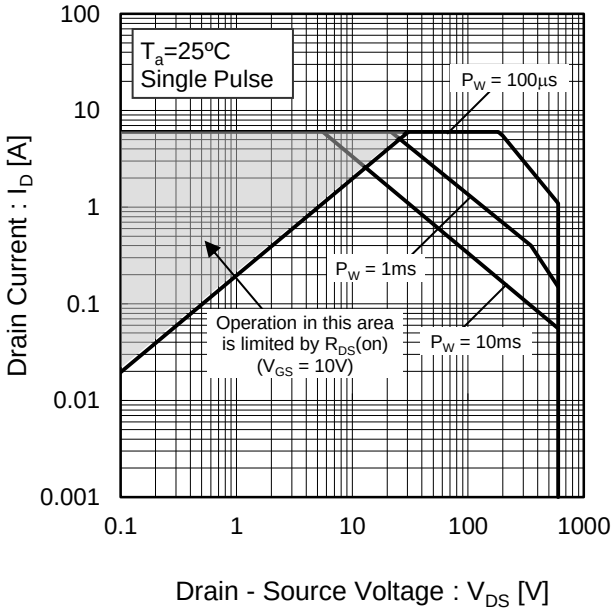
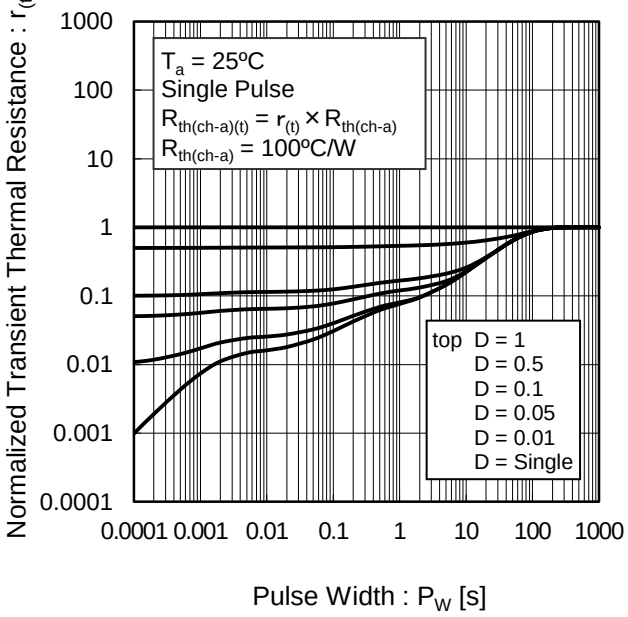



Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width



## ●Electrical characteristic curves

Fig.4 Avalanche Current vs Inductive Load

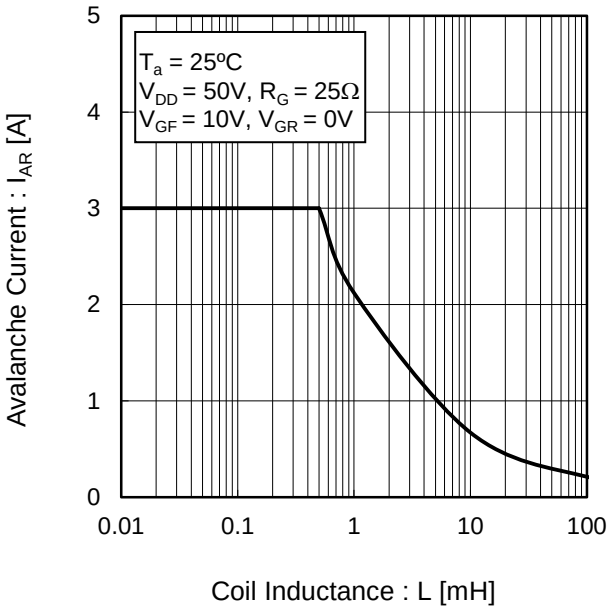



Fig.5 Avalanche Power Losses

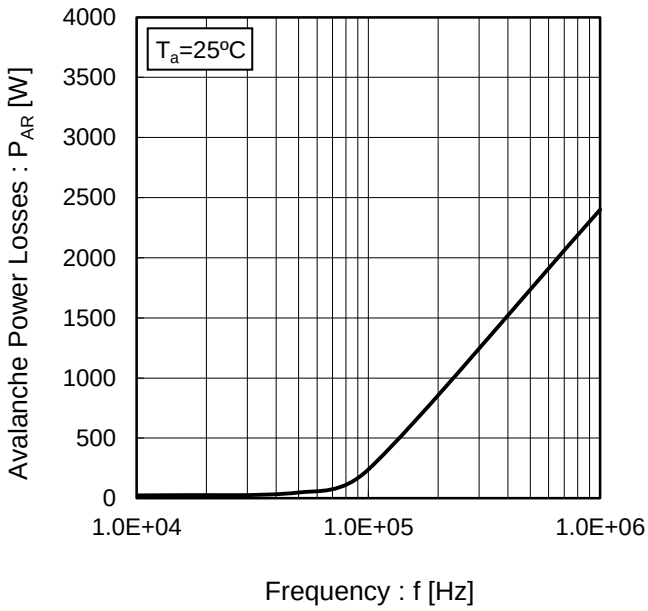
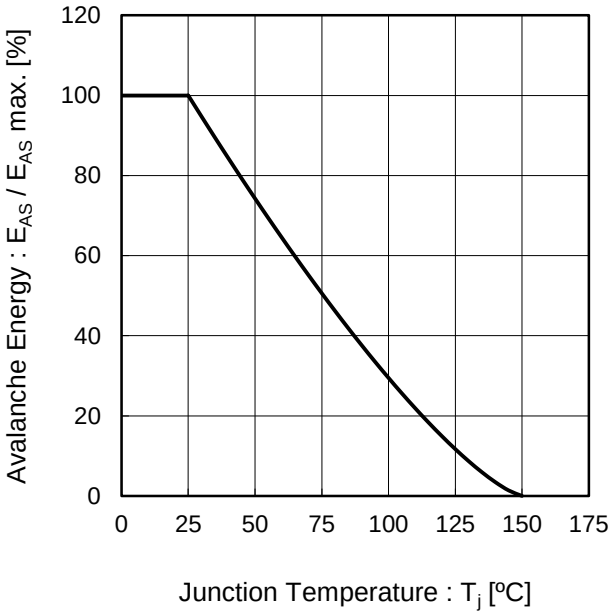



Fig.6 Avalanche Energy Derating Curve vs Junction Temperature



## ●Electrical characteristic curves

Fig.7 Typical Output Characteristics(I)

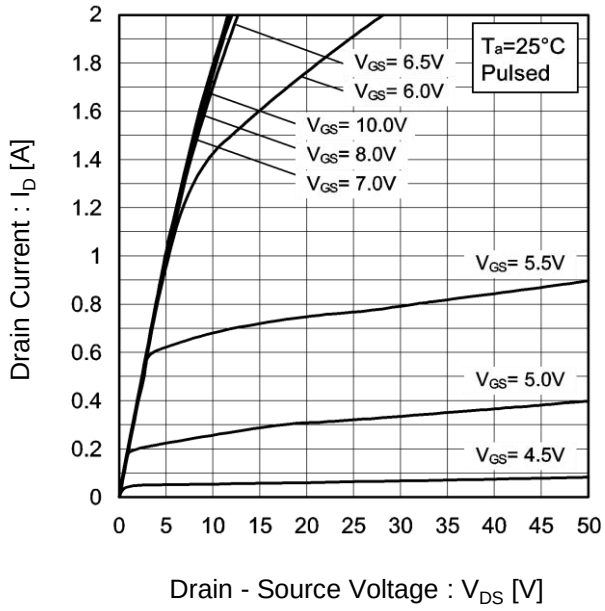



Fig.8 Typical Output Characteristics(II)

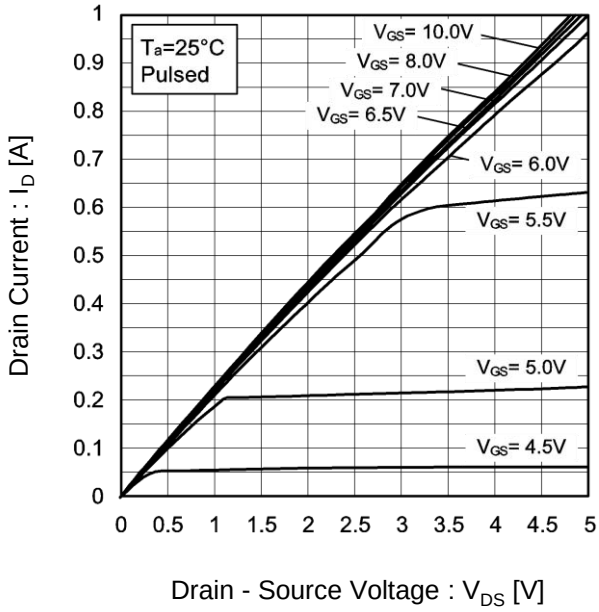



Fig.9 $T_j$ = 150°C Typical Output Characteristics(I)

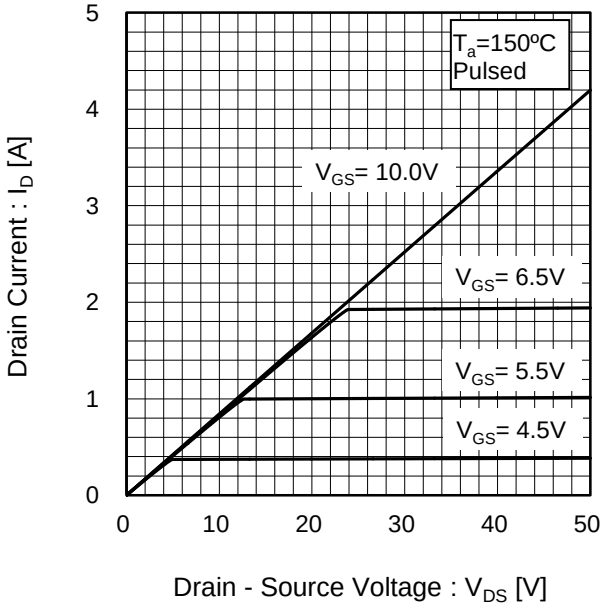
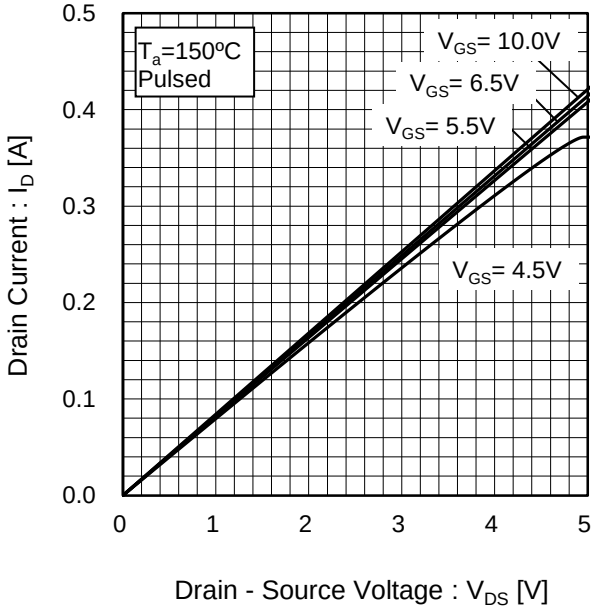



Fig.10 $T_j$ = 150°C Typical Output Characteristics(II)



## ●Electrical characteristic curves

Fig.11 Breakdown Voltage vs. Junction Temperature

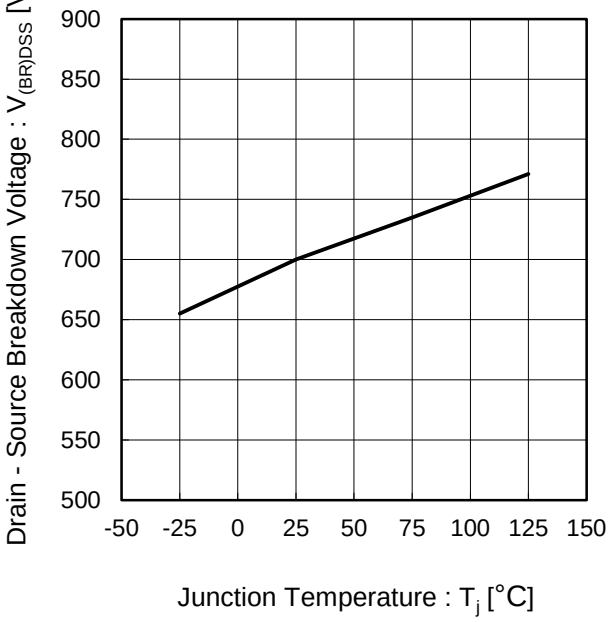



Fig.12 Typical Transfer Characteristics

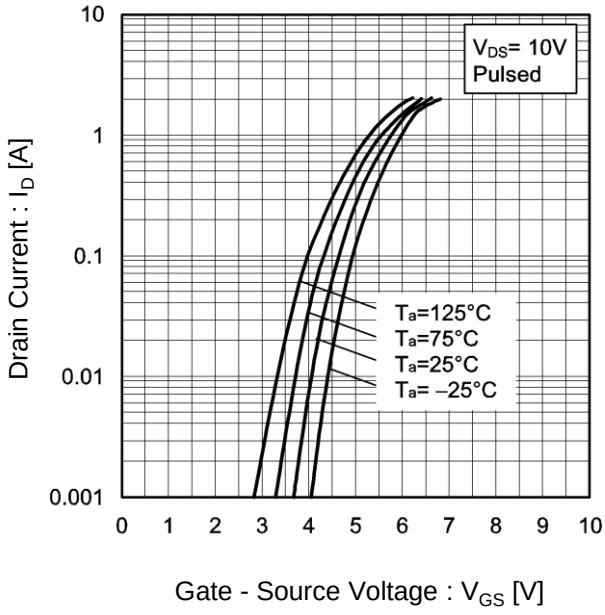



Fig.13 Gate Threshold Voltage vs. Junction Temperature

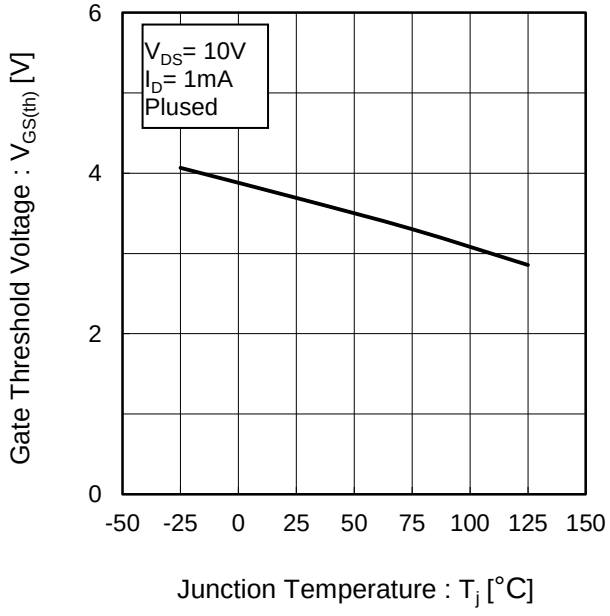
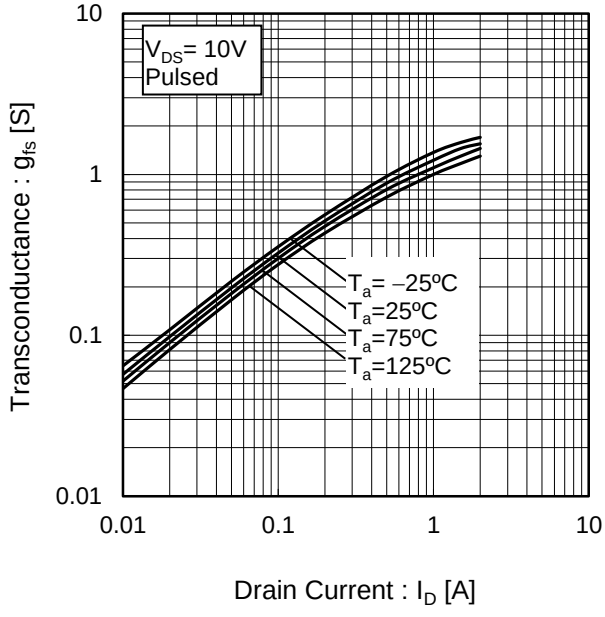



Fig.14 Transconductance vs. Drain Current



## ●Electrical characteristic curves

Fig.15 Static Drain - Source On - State Resistance vs. Gate Source Voltage

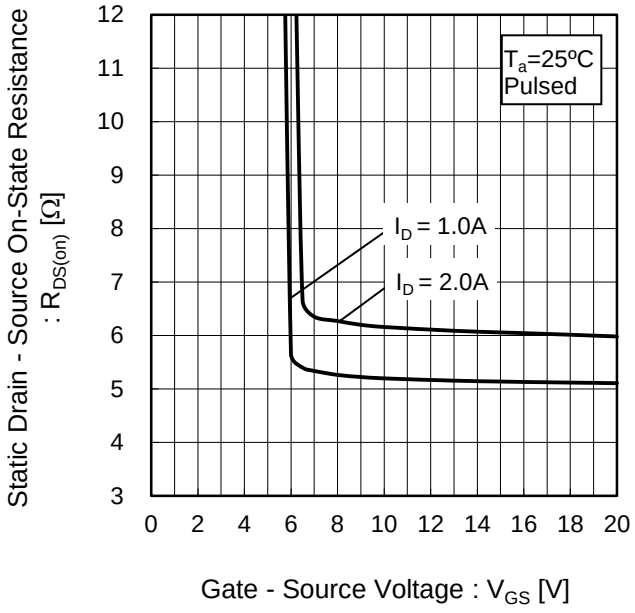



Fig.16 Static Drain - Source On - State Resistance vs. Junction Temperature

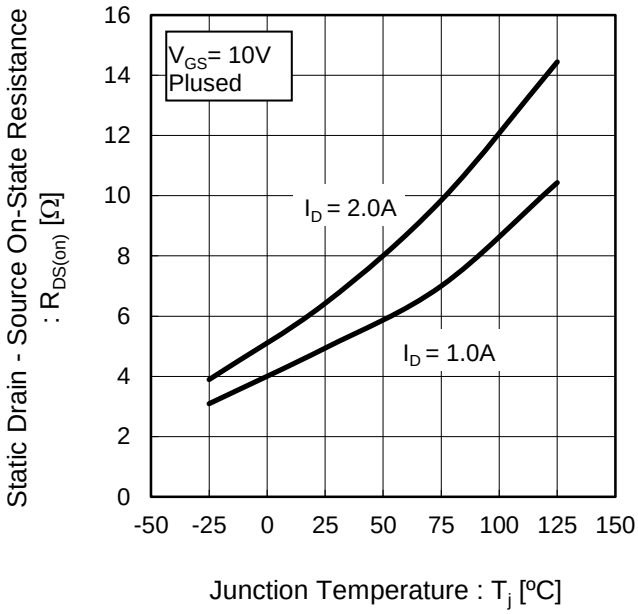
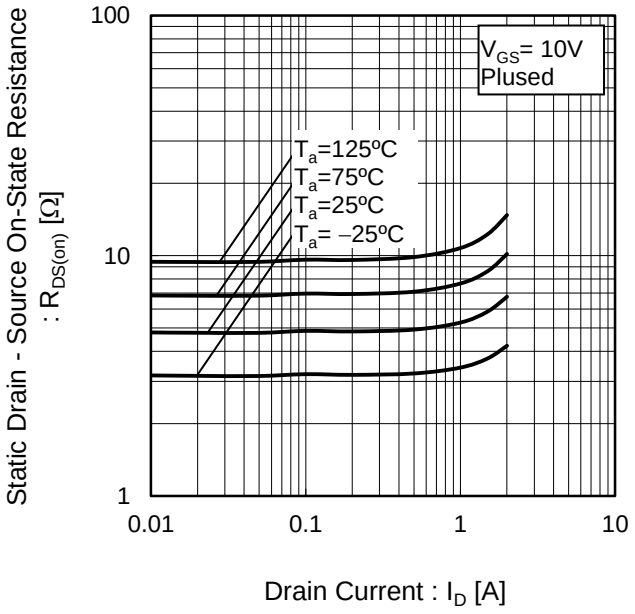



Fig.17 Static Drain - Source On - State Resistance vs. Drain Current



## ●Electrical characteristic curves

Fig.18 Typical Capacitance vs. Drain - Source Voltage

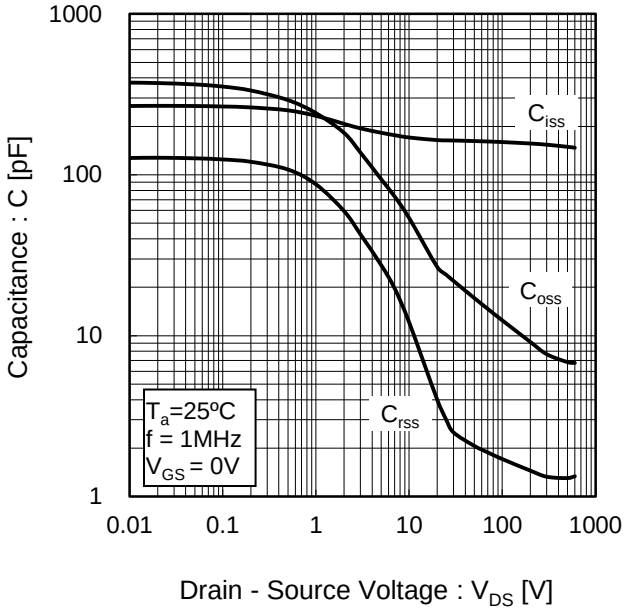



Fig.19 Coss Stored Energy

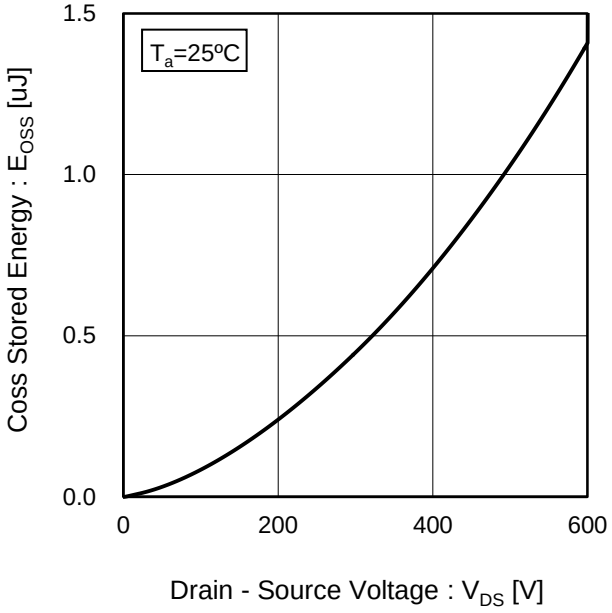



Fig.20 Switching Characteristics

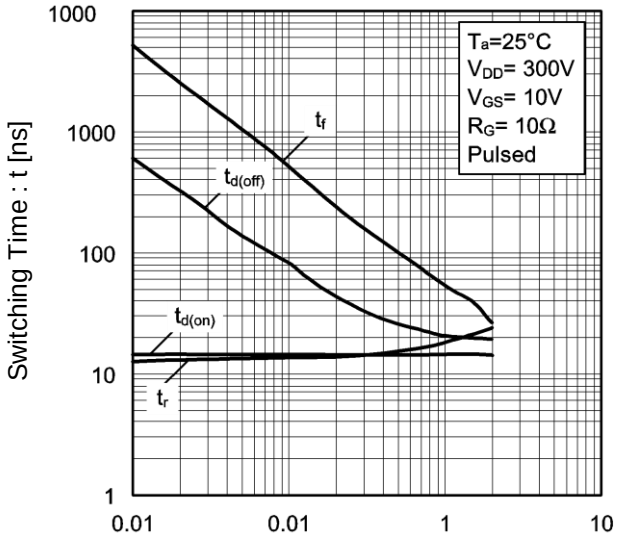
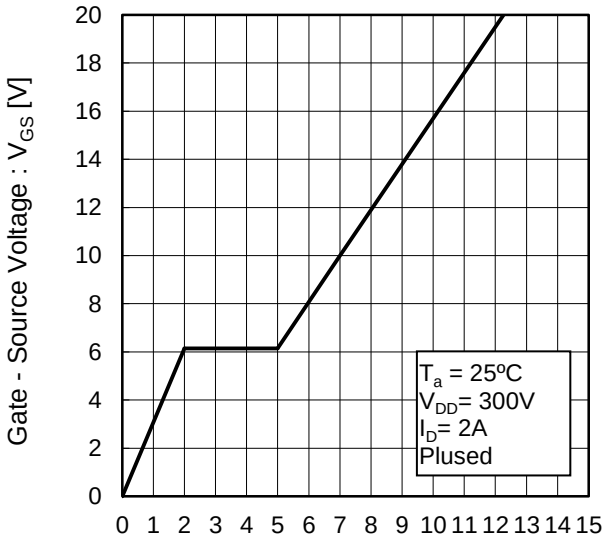



Fig.21 Dynamic Input Characteristics



## ●Electrical characteristic curves

Fig.22 Inverse Diode Forward Current vs. Source - Drain Voltage

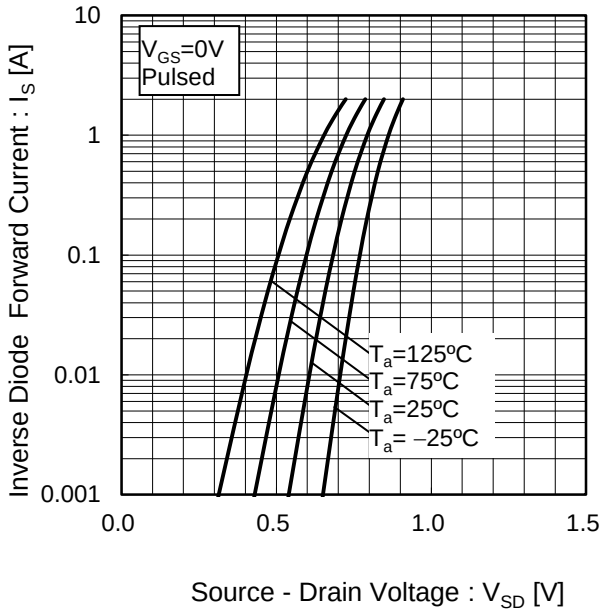
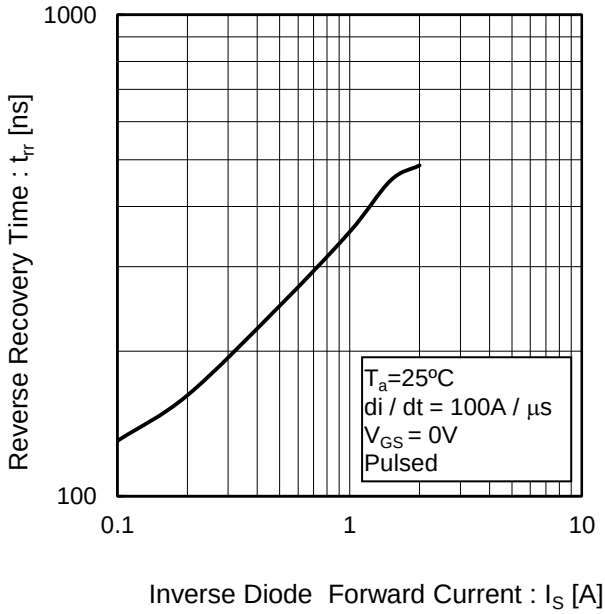



Fig.23 Reverse Recovery Time vs.Inverse Diode Forward Current



## ●Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

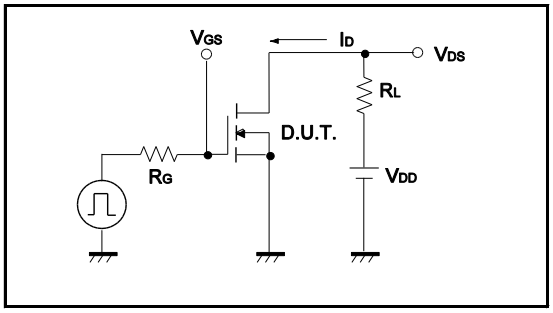



Fig.1-2 Switching Waveforms

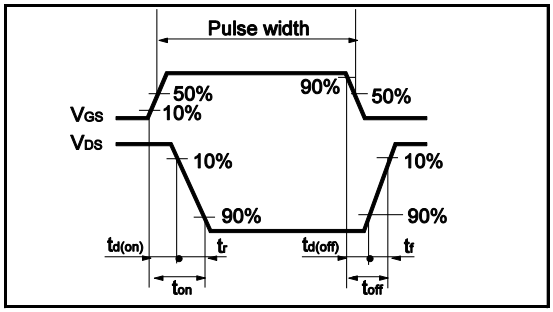



Fig.2-1 Gate Charge Measurement Circuit

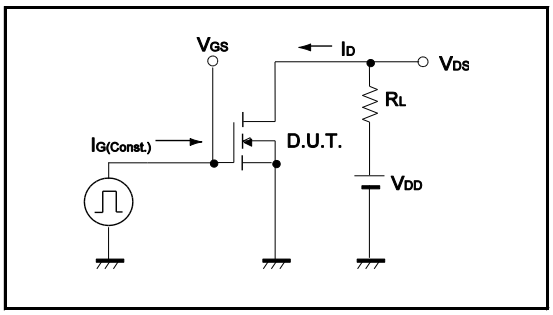



Fig.2-2 Gate Charge Waveform

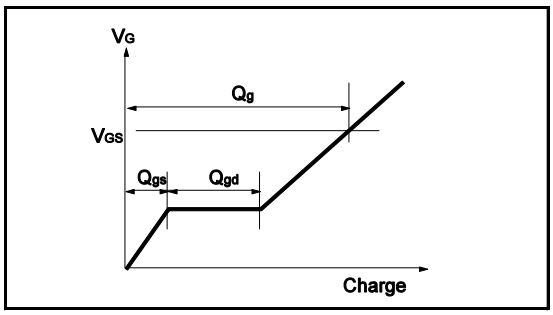



Fig.3-1 Avalanche Measurement Circuit

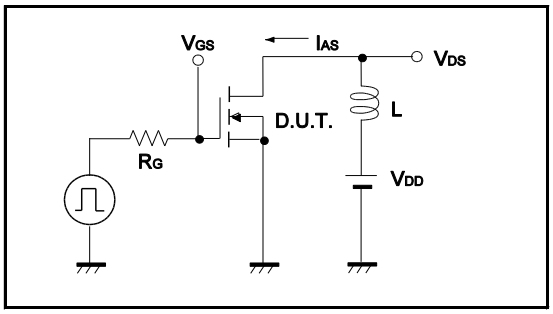



Fig.3-2 Avalanche Waveform

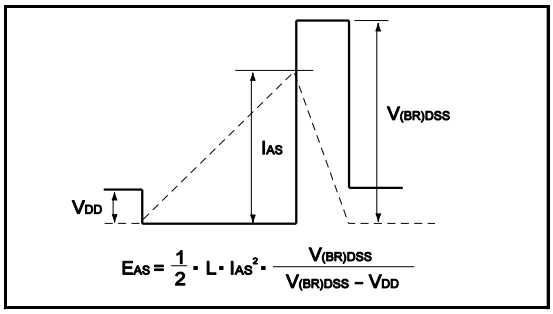



Fig.4-1 dv/dt Measurement Circuit

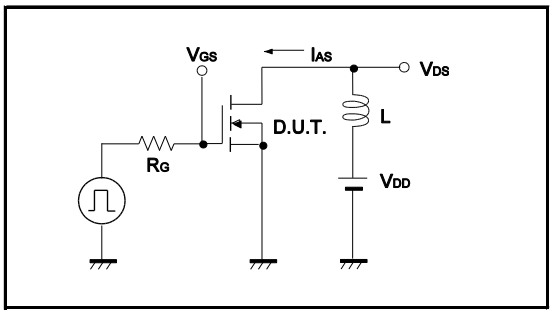



Fig.4-2 dv/dt Waveform

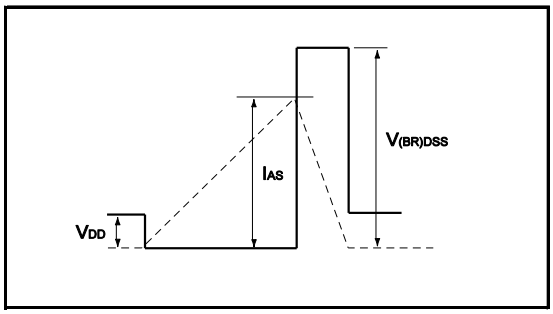



Fig.5-1 di/dt Measurement Circuit

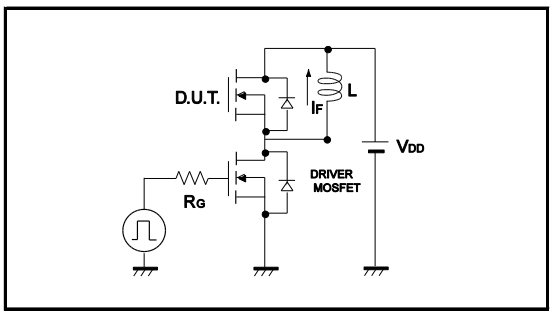
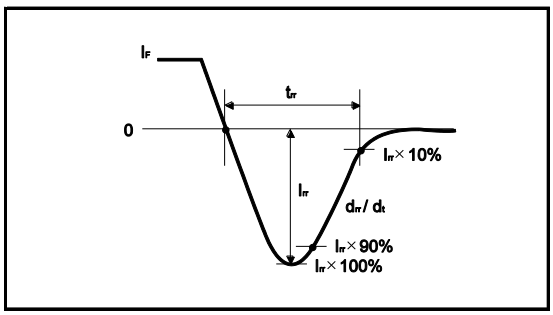
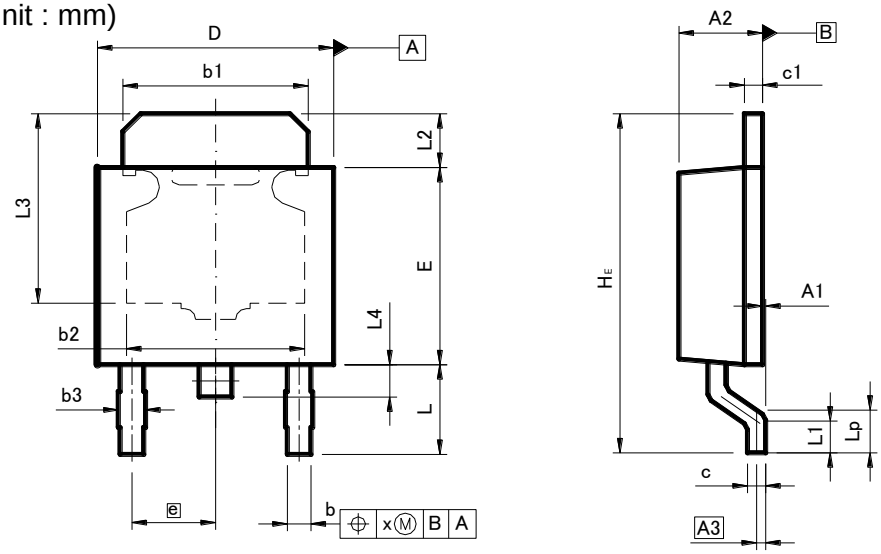


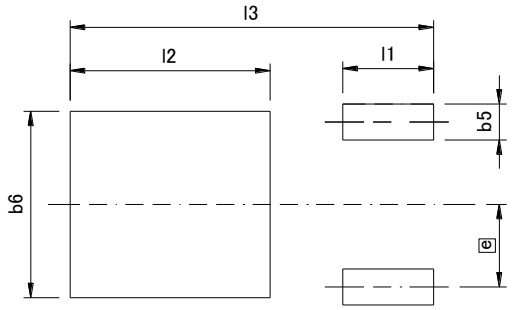

Fig.5-2 di/dt Waveform



●**Dimensions** (Unit : mm)

**CPT3**




Pattern of terminal position areas
[Not a recommended pattern of soldering pads]

| DIM | MILIMETERS | | INCHES | |
|---|---|---|---|---|
| | MIN | MAX | MIN | MAX |
| A1 | 0.00 | 0.15 | 0.000 | 0.006 |
| A2 | 2.20 | 2.50 | 0.087 | 0.098 |
| A3 | 0.25 | | 0.010 | |
| b | 0.55 | 0.75 | 0.022 | 0.030 |
| b1 | 5.00 | 5.30 | 0.197 | 0.209 |
| b2 | 5.00 | | 0.197 | |
| b3 | 0.75 | | 0.030 | |
| c | 0.40 | 0.60 | 0.016 | 0.024 |
| c1 | 0.40 | 0.60 | 0.016 | 0.024 |
| D | 6.30 | 6.70 | 0.248 | 0.264 |
| E | 5.40 | 5.80 | 0.213 | 0.228 |
| e | 2.30 | | 0.091 | |
| HE | 9.00 | 10.00 | 0.354 | 0.394 |
| L | 2.20 | 2.80 | 0.087 | 0.110 |
| L1 | 0.80 | 1.40 | 0.031 | 0.055 |
| L2 | 1.20 | 1.80 | 0.047 | 0.071 |
| L3 | 5.30 | | 0.209 | |
| L4 | 0.90 | | 0.035 | |
| Lp | 1.00 | 1.60 | 0.039 | 0.063 |
| x | – | 0.25 | – | 0.010 |

| DIM | MILIMETERS | | INCHES | |
|---|---|---|---|---|
| | MIN | MAX | MIN | MAX |
| b5 | – | 1.00 | – | 0.04 |
| b6 | – | 5.20 | – | 0.205 |
| l1 | – | 2.50 | – | 0.098 |
| l2 | – | 5.50 | – | 0.217 |
| l3 | – | 10.00 | – | 0.394 |

Dimension in mm / inches

## Notes

1) The information contained herein is subject to change without notice.

2) Before you use our Products, please contact our sales representative and verify the latest specifications :

3) Although ROHM is continuously working to improve product reliability and quality, semiconductors can break down and malfunction due to various factors.
Therefore, in order to prevent personal injury or fire arising from failure, please take safety measures such as complying with the derating characteristics, implementing redundant and fire prevention designs, and utilizing backups and fail-safe procedures. ROHM shall have no responsibility for any damages arising out of the use of our Poducts beyond the rating specified by ROHM.

4) Examples of application circuits, circuit constants and any other information contained herein are provided only to illustrate the standard usage and operations of the Products. The peripheral conditions must be taken into account when designing circuits for mass production.

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6) The Products are intended for use in general electronic equipment (i.e. AV/OA devices, communication, consumer systems, gaming/entertainment sets) as well as the applications indicated in this document.

7) The Products specified in this document are not designed to be radiation tolerant.

8) For use of our Products in applications requiring a high degree of reliability (as exemplified below), please contact and consult with a ROHM representative : transportation equipment (i.e. cars, ships, trains), primary communication equipment, traffic lights, fire/crime prevention, safety equipment, medical systems, servers, solar cells, and power transmission systems.

9) Do not use our Products in applications requiring extremely high reliability, such as aerospace equipment, nuclear power control systems, and submarine repeaters.

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